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Specification

MCT043EC6W480272LML



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1. Revision History

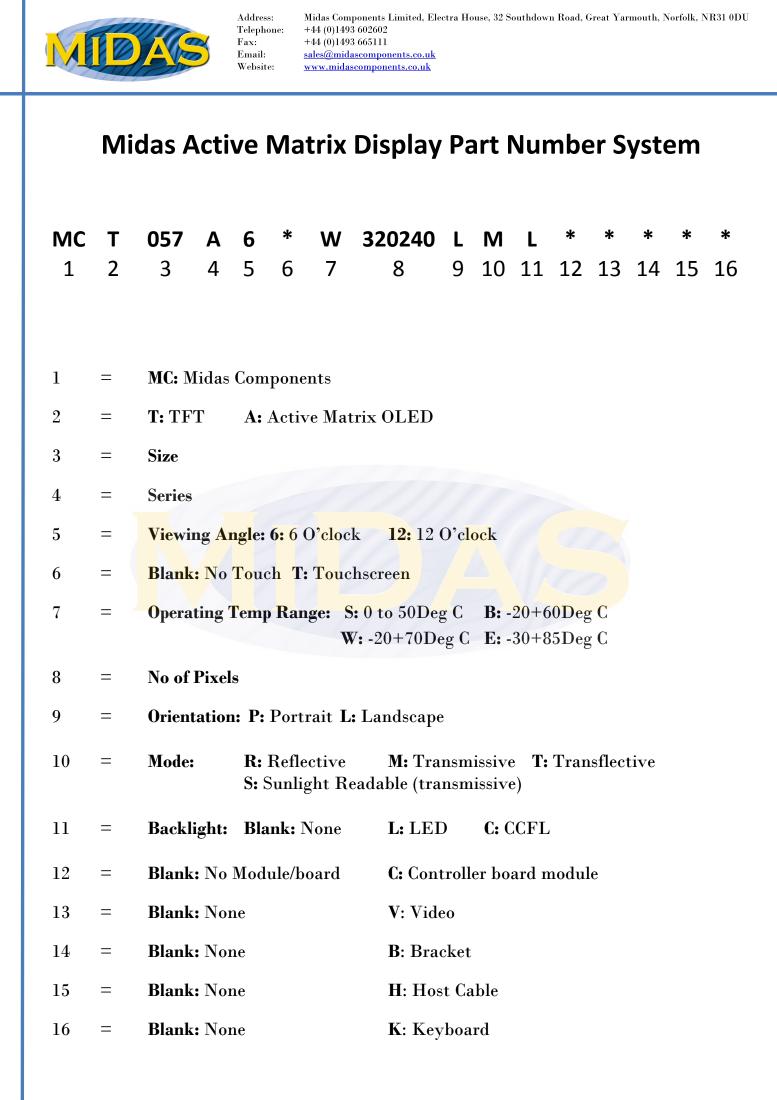
DATE	VERSION	REVISED PAGE NO.	Note
2011/01/05	1		First issue



2. General Specification

This product is composed of a TFT LCD panel, driver ICs, FPC, Control Board and a backlight unit. The following table described the features of T ÔV€I HÒÔÎ Y I Ì €ĠÏ &ŠT ŠÈ

- Dot Matrix: 480x 3(RGB) x272
- Module dimension:105.5 x 67.2 x 2.90 (max.) mm³
- View area: 95.04x53.856 mm²
- Dot pitch: 0.066 x 0.198 mm2
- LCD type: TFT, Negative, Transmissive
- View direction: 6 o'clock
- Backlight Type: LED, Normally White



4. Interface Pin Function

4.1. TFT LCD Panel Driving Section

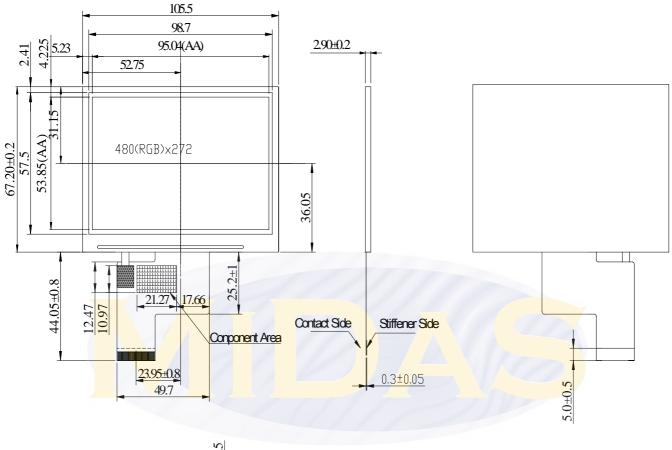
FPC Connector is used for the module electronics interface.

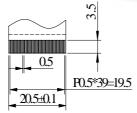
Pin No.	Symbol	I/O	Function	Remark
1	VLED-	Р	Power for LED backlight cathode	
2	VLED+	Р	Power for LED backlight anode	
3	GND	Р	Power ground	
4	VDD	Р	Power voltage	
5	R0	Ι	Red data (LSB)	
6	R1	Ι	Red data	
7	R2	Ι	Red data	
8	R3	Ι	Red data	
9	R4	I	Red data	
10	R5	Ι	Red data	
11	R6	Ι	Red data	D
12	R7	Ι	Red data (MSB)	
13	G0	Ι	Green data (LSB)	
14	G1	Ι	Green data	
15	G2	Ι	Green data	
16	G3	Ι	Green data	
17	G4	Ι	Green data	
18	G5	Ι	Green data	
19	G6	Ι	Green data	
20	G7	Ι	Green data (MSB)	
21	B0	Ι	Blue data (LSB)	
22	B1	Ι	Blue data	
23	B2	Ι	Blue data	
24	B3	Ι	Blue data	

25	B4	Ι	Blue data	
26	B5	Ι	Blue data	
27	B6	Ι	Blue data	
28	B7	Ι	Blue data (MSB)	
29	GND	Р	Power ground	
30	CLK	Ι	Pixel clock	
31	DISP	Ι	Display on/off	
32	NC	-	No connection	
33	NC	-	No connection	
34	DE	Ι	Data Enable	
35	NC	-	No connection	
36	GND	Р	Power ground	
37	NC	- /	No connection	(The
38	NC	- /	No connection	
39	NC	-	No connection	
40	NC	-	No connection	

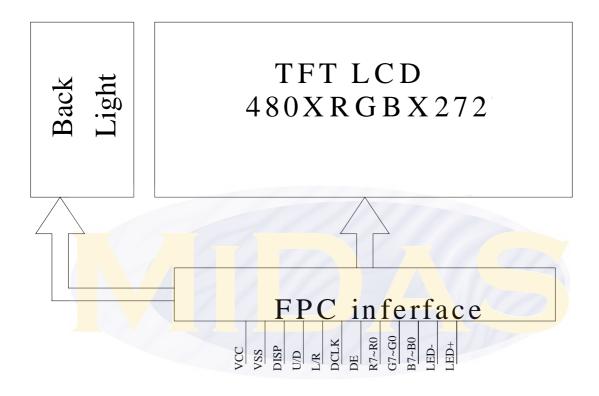
I: input, O: output, P: Power

5. Outline Dimension & Block Diagram





The non-specified tolerance of dimension is ±0.2mm



6. Display Control Instruction

6.1 Absolute Maximum Ratings.

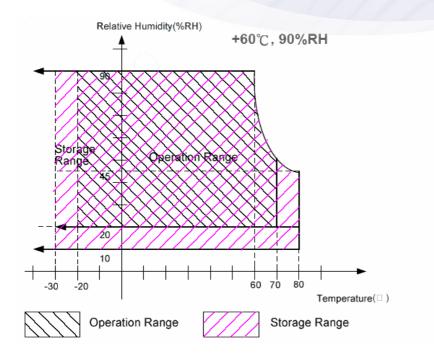
ltem	Symbol	Val	Values		Remark
	ey	Min	max	Unit	
Power Supply Voltages	VDD	-0.5	5.0	V	
Input signal voltage	Logic input	-0.5	5.0	V	
Operating Temperature	Тора	-20	70	。 C	Note3,4
Storage Temperature	Tst	-30	80	。 C	Note3,4
LED Reverse Voltage	Vr	-	1.2	V	Each LED Note2
LED Forward Current	IF	-	30	MA	Each LED

Note 1: The absolute maximum rating values of this product are not allowed to be exceeded at any times. A module should be used with any of the absolute maximum ratings exceeded, the characteristics of the module may not be recovered, or in an extreme condition, the module may be permanently destroyed.

Note 2: VR Conditions: Zener Diode 20mA

Note 3: 90% RH Max. (Max wet temp. is 60℃)

Maximum wet-bulb temperature is at 60°C or less. And No condensation (no drops of dew)



Note 4: In case of temperature below 0° C, the response time of liquid crystal (LC) becomes slower and the color of panel darker than normal one.

6.2 Typical operation conditions

ltem	Symbol		Values	Unit	Remark	
i i i i i i i i i i i i i i i i i i i	Cymsol	Min	TYP	max	onit	Kemark
Power voltage	VDD	3.1	3.3	3.5	V	
Current of driver	IVDD	-	TBD	25	mA	VDD =3.3V
Input logic high voltage	VIH	0.8* VDD	-	VDD	V	Note1
Input logic low voltage	VIL	GND	-	0.2 VDD	V	

Note1: CLK, DE, R0~ R7, G0~ G7, B0~ B7.

6.3 Backlight Driving Conditions

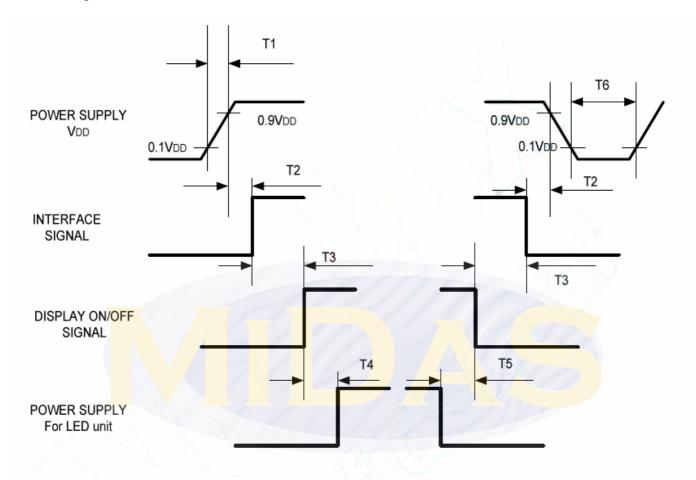
ltem	Symbol	Values			Unit	Remark
nem	Cymbol	Min	TYP	max	Onit	Kemark
Voltage for LED Bac <mark>klight</mark>	VL	25. <mark>2</mark>	27.9	31.5	V	Note 2
Current for LED Bac <mark>klig</mark> ht	IL	18	20	22	mA	
LED life time		20,000	-	/-//	Hr	Note1

Note 1: The "LED life time" is defined as the module brightness decrease to 50% original brightness that the ambient temperature is 25° C and IL =20mA. The LED lifetime could be decreased if operating IL is lager than 20 mA.

Note 2: The LED Supply Voltage is defined by the number of LED at Ta=25 $^\circ\!\!\mathbb{C}$ and IL =20mA.

6.4 Power Sequence

To prevent a latch-up or DC operation of the LCD module, the power on/off sequence should be as the diagram below.



Symbol	Specification	Symbol	Specification
Т1	$0 \leq T1 \leq 10 \text{ msec}$	Τ4	160 msec \leq T4
T2	$0 \leq T2 \leq 100 \text{ msec}$	Т5	160 msec \leq T5
Т3	$0 \leq T3 \leq 200 \text{ msec}$	Т6	1 msec ≦T6

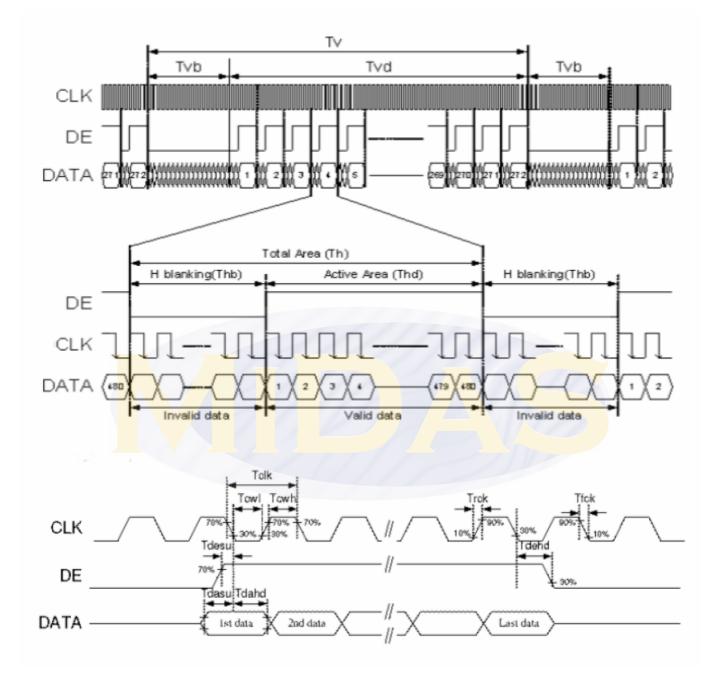
6.5 Timing Characteristics

6.5.1. Timing Conditions

Parallel DE mode RGB input timing table

Demonster	Cumple of		Value			
Parameter	Symbol	Min.	Min. Typ. I		– Unit	
CLK frequency	fclk	7	9	12	MHz	
DEV period time	Τv	277	288	400	Н	
DEV display area	Tvd		272		Н	
DEV blanking	Tvb	5	16	128	Н	
DEH period time	Th	520	525	800	CLK	
DEH display area	Thd		480	•	CLK	
DEH blanking	Thb	40	45	320	CLK	
CLK cy <mark>cle ti</mark> me	Tclk	83	110	143	ns	
Clock width <mark>of</mark> hig <mark>h leve</mark> l	Tcwh	<mark>4</mark> 0 / /	50	60	%	
Clock width of low level	Tcwl	40	50	60	%	
Clock rising time	trck		-	9	ns	
Clock falling time	tfck		-	9	ns	
Data Setup Time	tdesu	10	-	-	ns	
Data Hold Time	tdahd	10	-	-	ns	
DE Setup Time	tdesu	10	-	-	ns	
DE Hold Time	tdehd	10	-	-	ns	

6.5.2. Timing Diagram



7. Optical Characteristics

ltem	Symbol	Condition		Values	Unit	Remark	
nem	Symbol	Condition	Min.	Тур.	Max.	Unit	Nemark
	θι	Φ=180°(9 o'clock)	60	70			
Viewing angle	θ _R	Φ=0°(3 o'clock)	60	70	-		Note 1
(CR≥ 10)	θτ	Φ=90°(12 o'clock)	40	50	-	degree	
	θΒ	Φ=270°(6 o'clock)	60	70	Sala		
Descrete time	Ton		/-/	10	20	msec	Note 3
Response time	TOFF	870		15	30	msec	Note 3
Contrast rat <mark>io</mark>	CR		400	500	/	9.	Note 4
	Wx	Normal θ=Φ=0°	0.26	0.31	0.36	-	Note 2 Note 5
Color chromaticity	Wy		0.28	0.33	0.38	-	Note 6
Luminance	L	\sim	400	500	-	cd/m²	Note 6
Luminance uniformity	Yu		70	75	-	%	Note 7

Test Conditions:

V_{DD}=3.3V, I_L=20mA (Backlight current), the ambient temperature is 25°C.
 The test systems refer to Note 2.

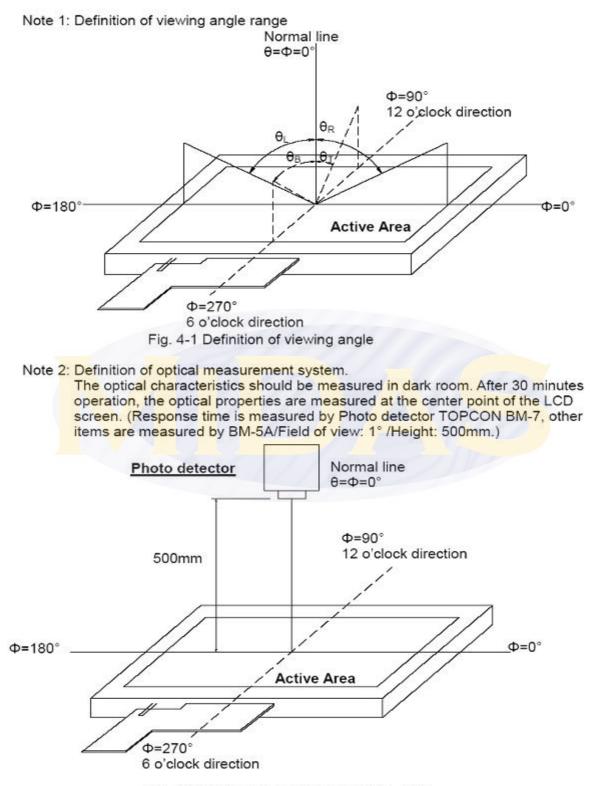
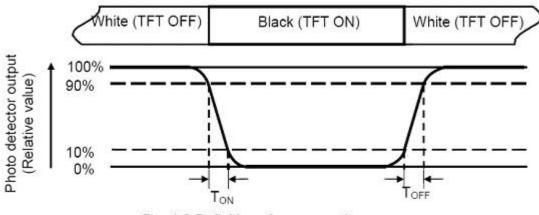
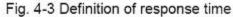


Fig. 4-2 Optical measurement system setup

Note 3: Definition of Response time

The response time is defined as the LCD optical switching time interval between "White" state and "Black" state. Rise time (T_{ON}) is the time between photo detector output intensity changed from 90% to 10%. And fall time (T_{OFF}) is the time between photo detector output intensity changed from 10% to 90%.





Note 4: Definition of contrast ratio

Contrast ratio (CR) = Luminance measured when LCD on the "White" state

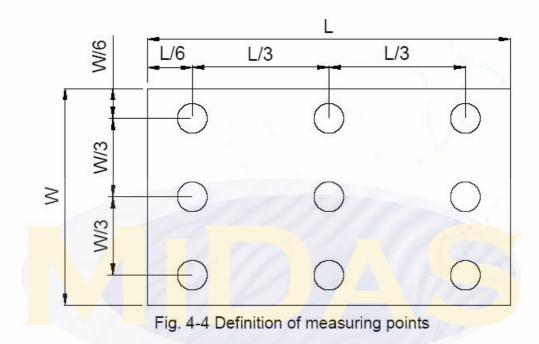
- Note 5: Definition of color chromaticity (CIE1931)
- Color coordinates measured at center point of LCD.
- Note 6: All input terminals LCD panel must be ground while measuring the center area of the panel. The LED driving condition is IL=20mA.

Note 7: Definition of Luminance Uniformity

Active area is divided into 9 measuring areas (Refer to Fig. 4-4).Every measuring point is placed at the center of each measuring area.

Luminance Uniformity (Yu) =
$$\frac{B_{min}}{B_{max}}$$

L-----Active area length W----- Active area width



B_{max}: The measured maximum luminance of all measurement position. **B**_{min}: The measured minimum luminance of all measurement position.

8. Absolute Maximum Ratings

ltem	Symbol	Min	Тур	Max	Unit
Operating Temperature	T _{OP}	-20		+70	°C
Storage Temperature	T _{ST}	-30		+80	°C

9. Electrical Characteristics

		Values				
ltem	Symbol	Min	ТҮР	max	Unit	Remark
Operating voltage	VDD	3.1	3.3	3.5	V	
Input high v <mark>oltag</mark> e	VIH	0.8*VDD	-	VDD	V	
Input low vo <mark>ltage</mark>	VIL	GND	- /	0.2*VDD	V	
Output high <mark>vo</mark> lta <mark>ge</mark>	VOH	VDD-0.3		VDD	V	
Output low voltage	VOL	0	/ -	0.3	V	
Current Consumption	IVCI	53.5	-	80.25	mA	VCC=2.5V
Power Consumption	PLCD	133.8		200-	mW	VCC=2.5V

10. Backlight Information

LED driving conditions

			Values			
Item	Symbol	Min	ТҮР	max	Unit	Remark
LED Voltage	VL	25.2	27.9	31.5	V	
LED Current	IF	-	20	-	MA	
Power Consumption	PLED	-	558	-	MW	

Note 1 : Ta = 25 _

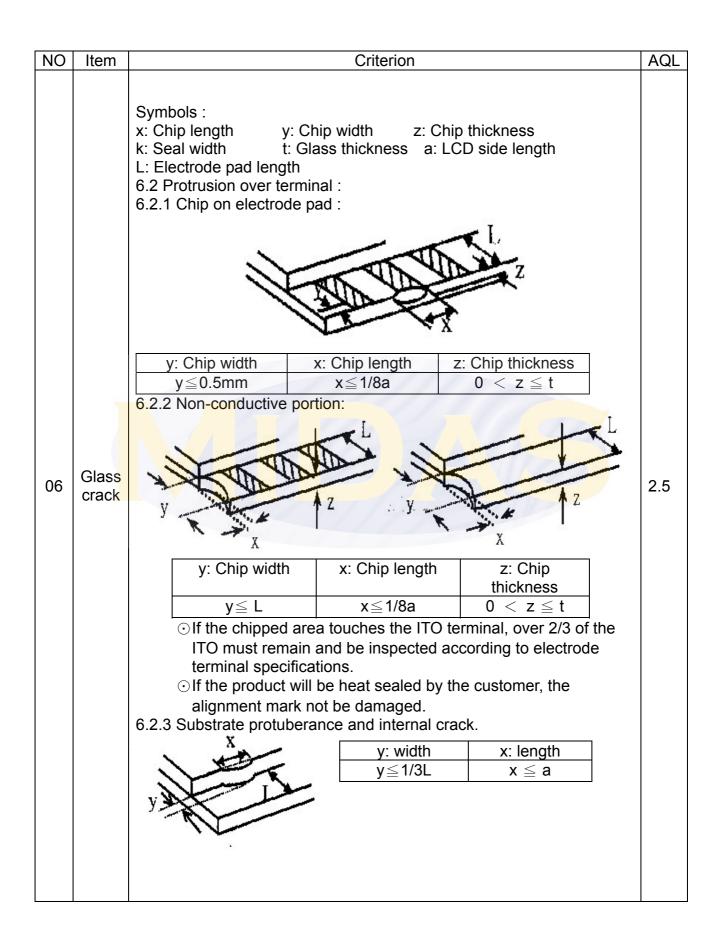
Note 2 : Brightess to be decreased to 50% of the initial value



11. Inspection specification

NO	Item	Criterion					
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect. 					
02	Black or white spots on LCD (display only)	than three v 2.2 Densely sp 3mm	 2.1 White and black spots on display ≤0.25mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 				
03	LCD black spots, white spots, contaminatio	3.1 Round type Φ=(x + y) /	2			2.5	
	n (non-display)	3.2 Line type :	(As follow Length	ring drawing) Width	Acceptable Q TY		
				W≦0.02	Accept no dense	2.5	
		1	L≦3.0 L≦2.5	$\begin{array}{c} 0.02\!<\!W\!\leq\!0.03\\ 0.03\!<\!W\!\leq\!0.05 \end{array}$	2		
				0.05 <w< td=""><td>As round type</td><td>Ц</td></w<>	As round type	Ц	
	Polarizer bubbles	not easy to find check in specify direction.		lge using black sp Size Φ Φ≦0.20	ot specifications, Acceptable Q TY Accept no		
04					dense 3	2.5	
				$0.50 < \Phi \le 1.00$	2		
				1.00<Ф	0		
		Total Q TY 3					

NO	Item		Criterion		AQL
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination			
06	Chipped glass	Symbols Define: x: Chip length y:	Chip width z: Ch Glass thickness a: I face and crack betwo v Chip width Not over viewing area Not exceed 1/3k e chips, x is total leng	hip thickness _CD side length een panels: x: Chip length $x \le 1/8a$ th of each chip. x: Chip length $x \le 1/8a$ $x \le 1/8a$	2.5



NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB · COB	 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB X * Y<=2mm² 	 2.5 2.5 2.5 2.5 0.65 2.5 2.5 2.5 2.5 2.5 2.5
11	Soldering	 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB. 	2.5 2.5 2.5 0.65

NO	Item	Criterion	AQL
12	General appearance	 12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it causes the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet. 12.9 LCD pin loose or missing pins. 12.10 Product packaging must the same as specified on packaging specification sheet. 12.11 Product dimension and structure must conform to product specification sheet. 	2.5 0.65 2.5 2.5 2.5 2.5 2.5 2.5 0.65 0.65 0.65 0.65

12. Precautions in use of LCD Modules

- 1. Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- 2. Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- 3. Don't disassemble the LCM.
- 4. Don't operate it above the absolute maximum rating.
- 5. Don't drop, bend or twist LCM.
- 6. Soldering: only to the I/O terminals.
- 7. Storage: please storage in anti-static electricity container and clean environment.
- 8. T aa have the right to change the passive components

(Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)

9. T aa have the right to change the PCB Rev.

13. Material List of Components for RoHs

1. T a me hereby declares that all of or part of products, including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

ÁÁExhibit A: The Harmful Material List

Á	#Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
	Limited	100	1000	1000	1000	1000	1000
	Value	ppm	ppm	ppm	ppm	ppm	ppm
	Above limited value is set up according to RoHS.						

- 2. Process for RoHS requirement :
 - (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
 - (2) Heat-resistance temp. :

Reflow : 250° C, 30 seconds Max. ;

Connector soldering wave or hand soldering : 320° C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : 235±5 $^\circ\!\mathrm{C}\,$;

Recommended customer's soldering temp. of connector : 280° C, 3 seconds.

14. Recommendable storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module